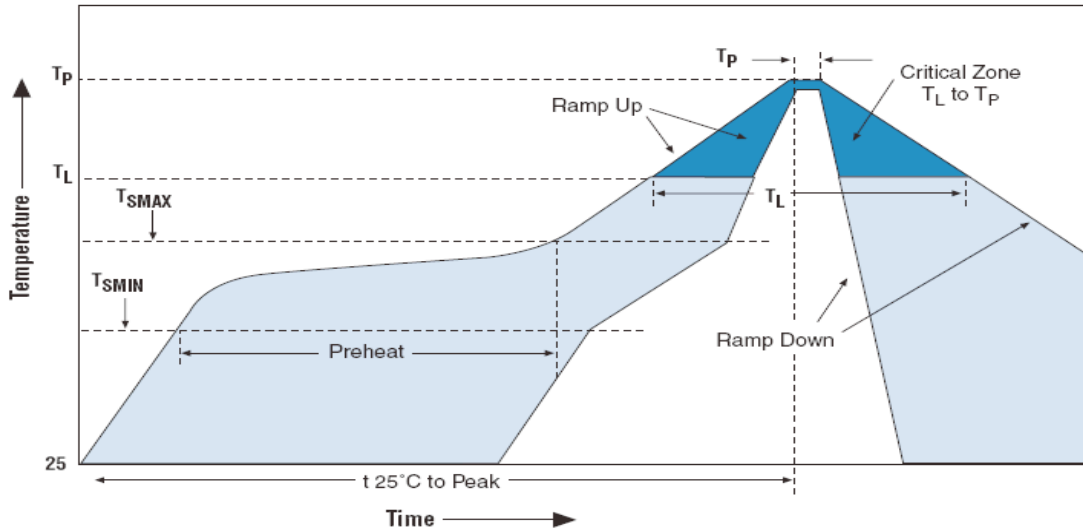


Lead-Free Reflow Profile Recommendation (IPC/JEDEC J-STD-020C)

Reflow Parameter	Lead Free Assembly
Minimum preheat temperature (TsMIN)	150 °C
Maximum preheat temperature (TsMAX)	200 °C
Preheat time	60-180 seconds
TsMAX to TL ramp-up rate	3 °C/second maximum
Time above temperature TL (tL)	217 °C 60-120 seconds
Peak temperature (TP)	245 °C ~260 °C(recommended 250 °C)
Time 25 °C to TP	6 minute maximum
Time within 5 ° of peak TP	10-20 seconds
Ramp-down rate	4 °C/second maximum

IR/Convection Reflow Profile (IPC/JEDEC J-STD-020C)



Wave soldering

Maximum peak temperature: 250 °C – 260 °C for 3-5 seconds max. (250 °C max. recommended)